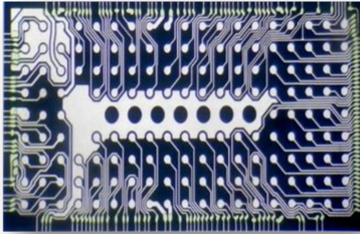
MIS

Molded Interconnect System



KEY FACTS

Pre-molded, routable, fine pitch leadframe

- Allows for complex designs where QFN cannot
- Smaller package footprint with thinner height

Cost competitive vs. FBGA/LGA

- Lower materials and via formation costs

Increased Package Performance

- Better electrical with shorter wire lengths
- Better grounding options
- Better thermal path compared to FBGA/LGA

MIS MARKET DRIVERS

QFN Package Limitations

- Pitch and routing limits
- Limited grounding options
- Package size and thickness

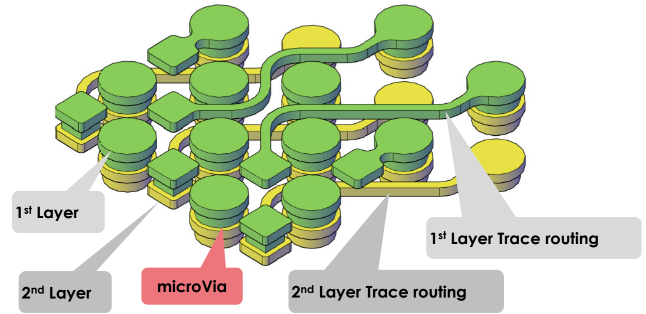
FBGA/LGA Package Limitations

- High material and via formation costs
- Not able to meet MSL Level 1

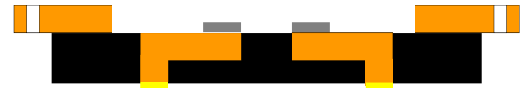
Alternative to FOWLP

- Interposer for fine pitch micro-bump Flip Chip fan-out

MIS routable metal lead frame

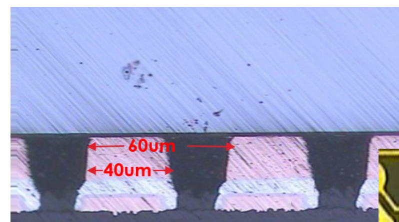


MIS lead frame is pre-molded

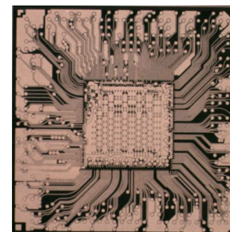


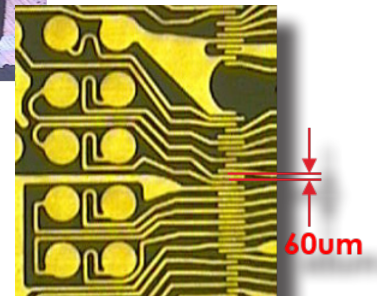
Side View of Pre-molded MIS

MIS lead frame has a fine pitch



X-section View of Fine Pitch Flip Chip





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